



Material declaration form

General Information			
IPC	1752	Version	2
Form type*	Distribute		
Sectionals*	Material information	Subsectionals*	A-D
	Manufacturing information		*: Required Field

Supplier Information			
Company name*	STMicroelectronics	Response Date*	2025-02-25
Contact name*	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact phone*	Refer to Supplier Comment section	Contact email*	Refer to Supplier Comment section
Authorized representative*	Antonella Lanzafame	Representative title	APMSMaterial Declaration champion
Representative phone*	Refer to Supplier Comment section	Representative email*	Refer to Supplier Comment section
Supplier comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty statement

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Legal statement

Supplier acceptance*	true	Legal declaration*	Standard
Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.			



Product				
Mfr item number	Mfr item name	Version	Manufacturing site	date
TSL339IPT	2D6R*V339AAL	A	BO2A	2025-02-25
	Amount	Unit of measure	Unit type	ST ECOPACK grade
	55	mg	Each	ECOPACK® 3
Identity	Authority			
Comment	ECOPACK® 3 is STMicroelectronics trade name for ROHS compliant device without use of any ROHS exemption and without Halogen nor Antimony			

Manufacturing information			
J-STD-020 MSL rating	Classification temperature	Number of reflow cycles	
1	260	3	
Bulk solder termination	Terminal plating	Terminal base alloy	Comment
Not Applicable	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy	0

Package designator	Package size	Number of instances	Shape
DSO	5x4.4	14	gull wing
Comment			
Comment	6R TSSOP 14 BODY 4.4 PITCH 0.65		

QueryList : RoHS Directive 2011/65/EU - 8 June 2011 – Annex II amended by Delegated Directive 2015/863 - 31 March 2015	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Exemption Id.	Description

QueryList : ELV directive : 2000/53/EC amended 2020/363_March 2020	Response
1 - Product(s) meets EU ELV requirements without any exemptions	true
2 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Exemption Id.	Description

QueryList : California Prop65 list, dated 3rd January 2025	Response		
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen	false		
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen	true		
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.234	alloy	4269

QueryList :Customer	Response
QUERY	Response

QueryList : Chinese RoHS , references : SJT 11364 – 2014 and GBT 26572 – 2014	Response			
QUERY	Response			
1 - Product(s) requires marking for the presence of restricted substances and must be marked with an Environmental Protection Use Period under China's Measures for Administration of the control of pollution by Electronic Information Products	false			
2 - Product(s) is eligible for marking with the e code under China's Measures for Administration of the control of pollution by Electronic Information Products	false			
Hazardous substance				
Lead (Pb)	Cadmium (Cd)	Mercury (Hg)	Hexavalent Chromium (Cr VI)	PBB & PBDE
O	O	O	O	O

QueryList : REACH-21st January 2025	Response			
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH	true			
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
,				
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Embedded article nor Homogeneous Material above the limits per the definition within REACH	true			
CategoryLevel_Name	CategoryLevel_Threshold	Amount in embedded article / Homogeneous material (mg)	Application - article / Homogeneous material	ppm in article /Homogeneous material
,				



QueryList : Responsible metals sourcing	Response
The component is containing at least one of the following metals : Cobalt , Gold , Tantalum , Tin , Tungsten.	true
The following metals are present is the component :	Gold, Tungsten,

QueryList : Korea Chemical Control Act_ 27 Dec 2017 update	Response
The Product does contain at least one of the substances listed in Chemical Control Act	false

QueryList : China GB 33372-2020 Limit standard for volatile organic compounds content in adhesives - 4 March 2020 application date 1st December 2020	Response
The product contains adhesives identified under GB 33372	true
All the adhesive impacted complies with GB 33372	true

QueryList:Stockholm Convention Persistent Organic Pollutants (POP)	Response
Product is compliant with Annex A, B and C of Stockholm Convention Persistent Organic Pollutants	true

QueryList: EU Ship Recycling Regulation No. 1257/2013	Response
Product contains hazardous materials listed in Annex II of EU Ship Recycling Regulation No.1257/2013 and 2009/16/EC Directive	False

PFAS/PTFE Declaration	Response
The product is containing at least one of the following PFAS substance: Polytetrafluoroethylene,Thiophenium, Triphenylsulfonium nonaflate, Trifluoroacetic anhydride	False

BPA Declaration	Response
Product does not contain Bisphenol A (Isopropylidenediphenol)	True

Montreal Protocol	Response
Product does not contain Ozone Depleting Substances based on Annex I to Annex VII of EU REGULATION (EC) No 1005/2009	True

Environmental Protection Agency:Toxic Substances Control Act (TSCA). Section 6(h)	Response
Product does not contain Phenol, isopropylated, phosphate (3:1)	True

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	2D6R*V339AAL		54.8200		5000000.0	1000001.0
Homogeneous material	Material group	Mass	Unit of measure	Level	Substance category	Substance	CAS	Exempt	Mass	Unit of measure	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or Dies or Wafer (choose)	M-011 Other inorganic materials	0.947	mg	supplier	die	Silicon(Si)	7440-21-3		0.916	mg	967265	16709
				supplier	metallisation	Aluminium(Al)	7429-90-5		0.008	mg	8448	146
				supplier	metallisation	Titanium(Ti)	7440-32-6		0.001	mg	1056	18
				supplier	metallisation	Tungsten(W)	7440-33-7		0.001	mg	1056	18
				supplier	Passivation	Silicon nitride(Si)	12033-89-5		0.002	mg	2112	36
				supplier	passivation	Silicon oxide	7631-86-9		0.019	mg	20063	347
Leadframe	M-004 Copper and its alloys	16.835	mg	supplier	alloy	Copper(Cu)	7440-50-8		16.163	mg	960083	294838
				supplier	alloy	Iron(Fe)	7439-89-6		0.380	mg	22572	6932
				supplier	alloy	Iron phosphide	1310-43-6		0.023	mg	1366	420
				supplier	alloy	Zinc(Zn)	7440-66-6		0.020	mg	1188	365
				supplier	metallization	Nickel(Ni)	7440-02-0		0.234	mg	13900	4269
				supplier	metallization	Palladium(Pd)	7440-05-3		0.006	mg	356	109
				supplier	metallization	Gold(Au)	7440-57-5		0.009	mg	535	164
Die attach	M-011 Other inorganic materials	0.143	mg	supplier	glue	Silver(Ag)	7440-22-4		0.126	mg	881119	2298
				supplier	glue	Isobornyl Metha	7534-94-3		0.007	mg	48951	128
				supplier	glue	Isobornyl acrylate	5888-33-5		0.007	mg	48951	128
				supplier	glue	Methyl acrylate	87320-05-6		0.003	mg	20979	55
Bonding wires	M-004 Copper and its alloys	0.095	mg	supplier	wire	Copper(Cu)	7440-50-8		0.095	mg	1000000	1733
Encapsulation	M-011 Other inorganic materials	36.800	mg	supplier	mold compound	Silica vitreous	60676-86-0		26.349	mg	716005	480646
				supplier	mold compound	Silicon oxide	7631-86-9		5.520	mg	150000	100693
				supplier	mold compound	Biphenyl epoxy	85954-11-6		2.760	mg	75000	50347
				supplier	mold compound	Phenol resin	26834-02-6		1.840	mg	50000	33564
				supplier	mold compound	Carbon black	1333-86-4		0.184	mg	5000	3356
				supplier	mold compound	Bismuth compo	7440-69-9		0.147	mg	3995	2682